

AUG 21 2001

Sheet 1 of 1

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| U.S. Department of Commerce, Patent and Trademark Office | | | | | | Atty Docket No. | | Serial No. | |
| | | | | | | M-10697 US | | 09/697,025 | |
| INFORMATION DISCLOSURE STATEMENT BY APPLICANT | | | | | | Applicant(s) | | | |
| (Use several sheets if necessary) | | | | | | MEHRDAD NIKOONAHAD ET AL. | | | |
| | | | | | | Filing Date | | Group | |
| | | | | | | October 26, 2000 | | 2623 | |
| U.S. Patent Documents | | | | | | | | | |
| *Examiner Initial | | Document Number | Date | Name | Class | Subclass | Filing Date If Appropriate | | |
| 28 | AA | 5,216,257 | 6/1/93 | Brueck et al. | | | | | |
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| | AF | | | | | | | | |
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| | AI | | | | | | | | |
| | AJ | | | | | | | | |
| | AK | | | | | | | | |
| Foreign Patent Documents | | | | | | | | | |
| | | | | | | | Translation | | |
| | | Document | Date | Country | Class | Subclass | Yes | No | |
| | AL | | | | | | | | |
| | AM | | | | | | | | |
| | AN | | | | | | | | |
| | AO | | | | | | | | |
| | AP | | | | | | | | |
| OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.) | | | | | | | | | |
| | AQ | <p style="text-align: center;">RECEIVED</p> <p style="text-align: center;">AUG 23 2001</p> <p style="text-align: center;">Technology Center 2300</p> | | | | | | | |
| | AR | | | | | | | | |
| | AS | | | | | | | | |
| Examiner | Date Considered | | | 1/8/04 | | | | | |
| <p>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.</p> | | | | | | | | | |

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| U.S. Department of Commerce, Patent and Trademark Office | | | | Atty Docket No. | | Application No. | |
| | | | | TNCR.183US0 | | 09/697,025 | |
| INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary) | | | | Applicant(s) | | Confirmation No. | |
| | | | | Mehrdad Nikoonahad, et al. | | 3437 | |
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| Foreign Patent Documents | | | | | | | Translation | |
|--------------------------|----|----------|------|---------|-------|----------|-------------|----|
| | | Document | Date | Country | Class | Subclass | Yes | No |
| | AL | | | | | | | |
| | AM | | | | | | | |

| OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.) | | |
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| 3/8 | AQ | R. Pfoff, et al., "In-Process Image Detecting Technique For Determination Of Overlay, And Image Quality For ASM-L Wafer Stepper", SPIE Vol. 1674 Optical/Laser Microlithography V (1992) pp. 594-608 |
| Examiner | Date Considered 1/8/04 | |

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